

Chong Wang

List of Publications by Year in descending order

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44
papers

845
citations

567281

15
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501196

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44
docs citations

44
times ranked

500
citing authors

| # | ARTICLE | IF | CITATIONS |
|----|--|------|-----------|
| 1 | Electrochemical behaviors of Janus Green B in through-hole copper electroplating: An insight by experiment and density functional theory calculation using Safranin T as a comparison. <i>Electrochimica Acta</i> , 2013, 92, 356-364. | 5.2 | 94 |
| 2 | Plating Uniformity of Bottom-up Copper Pillars and Patterns for IC Substrates with Additive-assisted Electrodeposition. <i>Electrochimica Acta</i> , 2014, 120, 293-301. | 5.2 | 77 |
| 3 | Prediction of a new leveler (N-butyl-methyl piperidinium bromide) for through-hole electroplating using molecular dynamics simulations. <i>Electrochemistry Communications</i> , 2012, 18, 104-107. | 4.7 | 57 |
| 4 | Computational analysis and experimental evidence of two typical levelers for acid copper electroplating. <i>Electrochimica Acta</i> , 2018, 273, 318-326. | 5.2 | 55 |
| 5 | Label-free diagnosis for colorectal cancer through coffee ring-assisted surface-enhanced Raman spectroscopy on blood serum. <i>Journal of Biophotonics</i> , 2020, 13, e201960176. | 2.3 | 52 |
| 6 | A comparison of typical additives for copper electroplating based on theoretical computation. <i>Computational Materials Science</i> , 2018, 147, 95-102. | 3.0 | 49 |
| 7 | Investigation of poly (1-vinyl imidazole co 1, 4-butanediol diglycidyl ether) as a leveler for copper electroplating of through-hole. <i>Electrochimica Acta</i> , 2018, 283, 560-567. | 5.2 | 49 |
| 8 | Optoplasmonic Hybrid Materials for Trace Detection of Methamphetamine in Biological Fluids through SERS. <i>ACS Applied Materials & Interfaces</i> , 2020, 12, 24192-24200. | 8.0 | 43 |
| 9 | Copolymer of Pyrrole and 1,4-Butanediol Diglycidyl as an Efficient Additive Leveler for Through-Hole Copper Electroplating. <i>ACS Omega</i> , 2020, 5, 4868-4874. | 3.5 | 37 |
| 10 | Compatible Ag ⁺ Complex-Assisted Ultrafine Copper Pattern Deposition on Poly(ethylene) Terephthalate. <i>ACS Applied Materials & Interfaces</i> , 2019, 11, 44811-44819. | 8.0 | 36 |
| 11 | Incorporation of Tin on copper clad laminate to increase the interface adhesion for signal loss reduction of high-frequency PCB lamination. <i>Applied Surface Science</i> , 2017, 422, 738-744. | 6.1 | 27 |
| 12 | Improved Uniformity of Conformal Through-Hole Copper Electrodeposition by Revision of Plating Cell Configuration. <i>Journal of the Electrochemical Society</i> , 2015, 162, D575-D583. | 2.9 | 21 |
| 13 | A better understanding of the capacity fading mechanisms of Li ₃ V ₂ (PO ₄) ₃ . <i>RSC Advances</i> , 2015, 5, 71684-71691. | 3.6 | 21 |
| 14 | Air-plasma surface modification of epoxy resin substrate to improve electroless copper plating of printed circuit board. <i>Vacuum</i> , 2019, 170, 108967. | 3.5 | 16 |
| 15 | Initiation electroless nickel plating by atomic hydrogen for PCB final finishing. <i>Chemical Engineering Journal</i> , 2016, 306, 117-123. | 12.7 | 15 |
| 16 | Study on brown oxidation process with imidazole group, mercapto group and heterocyclic compounds in printed circuit board industry. <i>Journal of Adhesion Science and Technology</i> , 2015, 29, 1178-1189. | 2.6 | 14 |
| 17 | Electrochemical Factors of Levelers on Plating Uniformity of Through-Holes: Simulation and Experiments. <i>Journal of the Electrochemical Society</i> , 2018, 165, E359-E365. | 2.9 | 14 |
| 18 | Convection-Dependent Competitive Adsorption between SPS and EO/PO on Copper Surface for Accelerating Trench Filling. <i>Journal of the Electrochemical Society</i> , 2019, 166, D93-D98. | 2.9 | 14 |

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|----|--|-----|-----------|
| 19 | Improving wettability of photo-resistive film surface with plasma surface modification for coplanar copper pillar plating of IC substrates. <i>Applied Surface Science</i> , 2017, 411, 82-90. | 6.1 | 13 |
| 20 | Investigation of polyvinylpyrrolidone as an inhibitor for trench super-filling of cobalt electrodeposition. <i>Journal of the Taiwan Institute of Chemical Engineers</i> , 2020, 112, 232-239. | 5.3 | 13 |
| 21 | Multiphysics coupling simulation of RDE for PCB manufacturing. <i>Circuit World</i> , 2015, 41, 20-28. | 0.9 | 12 |
| 22 | Enhancing adhesion performance of no-flow prepreg to form multilayer structure of printed circuit boards with plasma-induced surface modification. <i>Surface and Coatings Technology</i> , 2018, 333, 24-31. | 4.8 | 12 |
| 23 | Whisker inhibited Sn-Bi alloy coating on copper surface to increase copper bonding strength for signal loss reduction of PCB in high-frequency. <i>Applied Surface Science</i> , 2020, 513, 145718. | 6.1 | 12 |
| 24 | Hydroquinone oriented growth control to achieve high-quality copper coating at high rate for electronics interconnection. <i>Journal of the Taiwan Institute of Chemical Engineers</i> , 2020, 112, 130-136. | 5.3 | 10 |
| 25 | Numerical simulation and experiments to improve throwing power for practical PCB through-holes plating. <i>Circuit World</i> , 2019, 45, 221-230. | 0.9 | 9 |
| 26 | Surface coarsening of carbon fiber/cyanate ester composite for adhesion improvement of electroless copper plating as conductive patterns. <i>Materials Chemistry and Physics</i> , 2020, 255, 123597. | 4.0 | 9 |
| 27 | Cyanide-free silver immersion deposition involving 3-mercapto-1-propanesulfonic acid for copper finishing. <i>Materials Chemistry and Physics</i> , 2020, 244, 122671. | 4.0 | 9 |
| 28 | Fabrication of silver electrically conductive adhesive to apply in through-hole filling for PCB interconnection. <i>Journal of Materials Science: Materials in Electronics</i> , 2016, 27, 9186-9190. | 2.2 | 8 |
| 29 | Preparation of rimose NiZnP electrode for hydrogen evolution reaction in alkaline medium by electroless and H ₂ SO ₄ etching. <i>Journal of Alloys and Compounds</i> , 2017, 719, 376-382. | 5.5 | 8 |
| 30 | Multi-physics coupling aid uniformity improvement in pattern plating. <i>Circuit World</i> , 2016, 42, 69-76. | 0.9 | 7 |
| 31 | PET Surface Modification with Inkjet-Printing Pd ²⁺ /Epoxy Resin Solution for Selective Electroless Copper Plating. <i>ACS Applied Electronic Materials</i> , 2022, 4, 149-157. | 4.3 | 7 |
| 32 | Improvement of plating uniformity for copper patterns of IC substrate with multi-physics coupling simulation. <i>Circuit World</i> , 2018, 44, 150-160. | 0.9 | 6 |
| 33 | Effect of 3-mercapto-1-propane sulfonate sulfonic acid and polyvinylpyrrolidone on the growth of cobalt pillar by electrodeposition. <i>Nanotechnology Reviews</i> , 2022, 11, 1209-1218. | 5.8 | 5 |
| 34 | Investigation of benzoquinone as a new type of Cu electroplating additive. , 2017, , . | | 3 |
| 35 | Communicationâ€”Localized Accelerator Pre-Adsorption to Speed Up Copper Electroplating Microvia Filling. <i>Journal of the Electrochemical Society</i> , 2019, 166, D467-D469. | 2.9 | 3 |
| 36 | Polymer-based Cu/Ag composite as seed layer on insulating substrate for copper addition of multi-dimensional conductive patterns. <i>Journal of the Taiwan Institute of Chemical Engineers</i> , 2021, 123, 254-260. | 5.3 | 3 |

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|----|---|-----|-----------|
| 37 | A Catalytic and Interfacing PEDOT:PSS/CuPc Polymerized on Cloth Fiber to Electro-Metalize Stretchable Copper Conductive Pattern. <i>Advanced Materials Interfaces</i> , 0, , 2101462. | 3.7 | 2 |
| 38 | Quick development of copper electroplating formula for via and trench filling by an experiential method. , 2020, , . | | 1 |
| 39 | Enhancing peel strength between liquid crystal polymer and copper with plasma treatment, surface oxidation, and silane coating. <i>Journal of Applied Polymer Science</i> , 2022, 139, . | 2.6 | 1 |
| 40 | Embedded Magnetic Solenoid Inductor Into Organic Packaging Substrate Using Lithographic via Technology for Power Supply Module Integration. <i>IEEE Transactions on Electron Devices</i> , 2022, , 1-7. | 3.0 | 1 |
| 41 | Electrochemical Investigation Cu Corrosion Behaviour of Electronic Circuit Board in Base Electrolyte. <i>Applied Mechanics and Materials</i> , 2014, 556-562, 141-144. | 0.2 | 0 |
| 42 | Preparation of electronic-grade CuO for copper electrodeposition of printed circuit boards. <i>Circuit World</i> , 2014, 40, 127-133. | 0.9 | 0 |
| 43 | Effects of additives on filling blind vias for HDI manufacture. , 2015, , . | | 0 |
| 44 | Preparation and Properties of Cyanate/Epoxy-based Composite with Thermal Conductive Silica Particles. <i>IOP Conference Series: Materials Science and Engineering</i> , 2018, 422, 012003. | 0.6 | 0 |